

2018

Fact Sheet

www.cobham.com/HiRel

The most important thing we build is trust

TRUSTED ACCREDITATION

Aeroflex Plainview (Cobham) received Category 1A Trusted Accreditation by the Defense Microelectronics Activity as a Microelectronics Trusted Source for DoD and all other U.S. government users. The scope of accreditation is for Packaging /Assembly.

Cobham in Plainview for over thirty-five years has been a leader in the Microelectronic packaging arena. We are well experienced in Chip-On-Board (COB), Chip and Wire, Surface Mount Technology (SMT), and Multi-Chip-Module (MCM) technology. All designed to operate in severe environments where performance, size and weight are the upmost critical parameters.

Cobham offers:

- One stop solution for your microelectronic assembly, evaluation, test and screening requirements
- Quick-turn capabilities available
- MIL-PRF-38534 compliant (Class H &K), ISO-9001-2000 and AS9100 certified
- Element evaluation and component screening
- Full turnkey and "design-to-spec" programs available
- Value-added services such as radiation testing, classified testing and COTS/commercial up screening
- Class 100,000 clean rooms for hybrid, SMT and box assembly
- Class 10,000 for thick film substrate manufacturing

PACKAGING / ASSEMBLY CAPABILITIES

- Wafer saw and electrical probe
- State-of-the Art gold ball bonding: 60µ pitch available
- Large Area - 16" x 13" bondable area
- 1 mil to 2 mil automatic gold ball bonding
- Gold and aluminum wedge bonding
- Heavy Aluminum - 4 mil to 20 mil wire
- Ribbon Bonding - 0.25 mil x 3 mil to 2 mil x 10 mil
- Vacuum brazing - Eutectic die and substrate attach
- Epoxy die bonding to 12µ placement accuracy
- Gap welding - beam lead diodes / wire / ribbon

- Active laser trim of thick and thin film resistors
- RF /Microwave tuning
- Hi-Rel Chip-On-Board assemblies / SMT
- Hermetic or epoxy package sealing
- Plastic packages / flip chips
- Transformers / coils
- Internal preseat visual
 - MIL-STD-883, method 2010 or 2017, Condition A or B
- Hermetic packages available
 - LCC, PGA, QFP, DIP, FP, TO cans, ring frame, Multi-Chip Modules (MCM)
- Solder dip - MIL-STD-883, method 2003

In addition to the Category 1A Trusted Accreditation, Cobham offers:

- Electrical test
 - Wafer level DC parametrics, memory, logic and analog IC testing, wafer probe and package IC testing, RF testing to 40GHz
- Burn-In Services
 - Static/Dynamic burn-in, Accelerated life test
- Environmental test per MIL-STD-883 test methods
 - Hermeticity - method 1014, condition A1, A2, C3
 - PIND - method 2020, condition A, B
 - X-Ray Radiographic - method 2012
 - Centrifuge - method 2001
 - Temp cycle - method 101
 - Mechanical shock variable vibration - method 2007
 - Thermal vacuum testing

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